**IGBT** Discretes

# DOSEMI

# IGBT

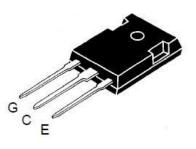
# DG30N12T2

**Molding Type Discretes** 

#### 1200V/30A IGBT with Anti-Parallel Diode

## **General Description**

DOSEMI IGBT Power Discretes provides ultra low conduction loss as well as short circuit ruggedness. They are designed for the applications such as general inverters and electronic welders.



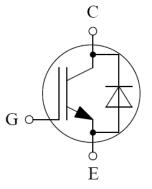
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#### Features

- Low V<sub>CE(sat)</sub> NPT IGBT technology
- Low switching loss
- Maximum junction temperature 150°C
- 10µs short circuit capability
- Square RBSOA
- V<sub>CE(sat)</sub> with positive temperature coefficient
- Fast & soft reverse recovery anti-parallel FWD
- Tight parameter distribution
- Lead free package

## **Typical Applications**

- Inverter for motor drive
- AC and DC servo drive amplifier
- Uninterruptible power supply
- Electronic welders



Equivalent Circuit Schematic

Symbol	Description	DG30N12T2	Units
V <sub>CES</sub>	Collector-Emitter Voltage	1200	V
V <sub>GES</sub>	Gate-Emitter Voltage	±20	V
T	Collector Current @ $T_C=25^{\circ}C$	58	٨
$I_{C}$	@ T <sub>C</sub> =100°C	30	A
I <sub>CM</sub>	Pulsed Collector Current t <sub>p</sub> =1ms	60	А
I <sub>F</sub>	Diode Continuous Forward Current	20	А
	@ T <sub>C</sub> =80°C	30	A
I <sub>FM</sub>	Diode Maximum Forward Current t <sub>p</sub> =1ms	60	А
P <sub>D</sub>	Maximum Power Dissipation @ T <sub>j</sub> =150°C	568	W
T <sub>jmax</sub>	Maximum Junction Temperature	150	°C
T <sub>jop</sub>	Operating Junction Temperature	-40 to +150	°C
T <sub>stg</sub>	Storage Temperature Range	-40 to +125	°C
Ts	Soldering Temperature, 1.6mm from case	260	്റ
	for 10s	200	C

## Absolute Maximum Ratings $T_C=25$ °C unless otherwise noted

**Electrical Characteristics of IGBT**  $T_C=25$  °C unless otherwise noted

#### **Off Characteristics**

Symbol	Parameter	Test Conditions	Min.	Тур.	Max.	Units
V <sub>(BR)CES</sub>	Collector-Emitter Breakdown Voltage	T <sub>j</sub> =25°C	1200			V
I <sub>CES</sub>	Collector Cut-Off Current	$V_{CE}=V_{CES}, V_{GE}=0V,$ $T_j=25$ °C			25	μΑ
I <sub>GES</sub>	Gate-Emitter Leakage Current	$V_{GE} = V_{GES}, V_{CE} = 0V,$ $T_j = 25^{\circ}C$			100	nA

#### **On Characteristics**

Symbol	Parameter	Test Conditions	Min.	Тур.	Max.	Units
$V_{GE(th)}$	Gate-Emitter Threshold Vol tage	$I_{C}=250\mu A, V_{CE}=V_{GE}, T_{j}=25^{\circ}C$	4.8	5.6	6.3	V
V <sub>CE(sat)</sub>	Collector to Emitter Saturation Voltage	$I_{C}=30A, V_{GE}=15V, T_{j}=25^{\circ}C$		2.30	2.75	V
		$I_{C}=30A, V_{GE}=15V, T_{i}=125^{\circ}C$		2.70		v

Symbol	Parameter	Test Conditions	Min.	Тур.	Max.	Units
t <sub>d(on)</sub>	Turn-On Delay Time			290		ns
t <sub>r</sub>	Rise Time			63		ns
t <sub>d(off)</sub>	Turn-Off Delay Time	$V_{CC}=600V, I_{C}=30A,$		270		ns
t <sub>f</sub>	Fall Time	$R_{G}=33\Omega, V_{GE}=\pm 15 V,$		285		ns
Eon	Turn-On Switching Loss	$T_j=25^{\circ}C$		3.82		mJ
$E_{\rm off}$	Turn-Off Switching Loss			2.04		mJ
t <sub>d(on)</sub>	Turn-On Delay Time			295		ns
t <sub>r</sub>	Rise Time			65		ns
t <sub>d(off)</sub>	Turn-Off Delay Time	V <sub>CC</sub> =600V,I <sub>C</sub> =30A,		280		ns
t <sub>f</sub>	Fall Time	$R_{G}=33\Omega, V_{GE}=\pm 15 V,$		340		ns
Eon	Turn-On Switching Loss	$T_{j}=125^{\circ}C$		4.78		mJ
E <sub>off</sub>	Turn-Off Switching Loss			2.97		mJ
Cies	Input Capacitance			1.68		nF
Coes	Output Capacitance	V <sub>CE</sub> =25V,f=1MHz,		0.26		nF
C <sub>res</sub>	Reverse Transfer Capacitance	V <sub>GE</sub> =0V		0.12		nF
Q <sub>G</sub>	Gate Charge	V <sub>CC</sub> =400V,I <sub>C</sub> =30A, V <sub>GE</sub> =15V		210		nC
I <sub>SC</sub>	SC Data	$\begin{array}{l} t_{P} \!$		225		А
R <sub>Gint</sub>	Internal Gate Resistance			none		Ω

### **Switching Characteristics**

## **Electrical Characteristics of Diode** $T_C=25$ °C unless otherwise noted

Symbol	Parameter	Test Conditions		Min.	Тур.	Max.	Units
$V_{\rm F}$	Diode Forward	$I_{\text{F}}=30A, V_{\text{GE}}=0V$	T <sub>j</sub> =25℃		2.25	2.70	V
	Voltage	$I_F=30A, V_{GE}=0V$	T <sub>j</sub> =125℃		2.35		v
Qr	Recovered		T <sub>j</sub> =25℃		1.8		μC
	Charge	I <sub>F</sub> =30A,	T <sub>j</sub> =125℃		3.8		μ
I <sub>RM</sub>	Peak Reverse	V <sub>R</sub> =600V,	T <sub>j</sub> =25℃		25		А
	Recovery Current	$R_G=33\Omega$ ,	T <sub>j</sub> =125℃		31		A
E <sub>rec</sub>	Reverse Recovery	$V_{GE}$ =-15V	T <sub>j</sub> =25℃		0.66		mJ
	Energy		T <sub>j</sub> =125℃		1.55		111J

### **Thermal Characteristics**

Symbol	Parameter	Тур.	Max.	Units
$R_{\theta JC}$	Junction-to-Case (per IGBT)		0.220	K/W
$R_{\theta JC}$	Junction-to-Case (per Diode)		0.542	K/W
$R_{\theta JA}$	Junction-to-Ambient	40		K/W

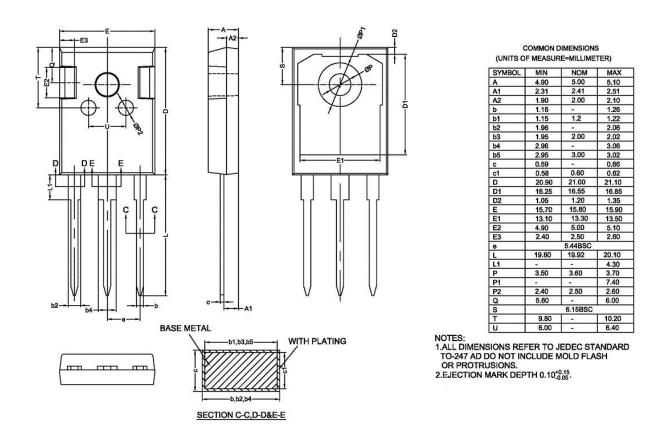
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Preliminary

## **Package Dimensions**

Dimensions in Millimeters



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